Product Change Notification

111609 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Product Change Notification

Change Notification #:	**111609 - 01**
Change Title:	**Intel® Solid State Drives PCN 111609-01, Transport Media Packaging Cushion Material Upgraded to Thermoformed HDPE (High Density Polyethylene) and Box/Pallet Dimension Changes Reason for Revision: To Notify Additional Customers**
Date of Publication:	**October 23, 2012**

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

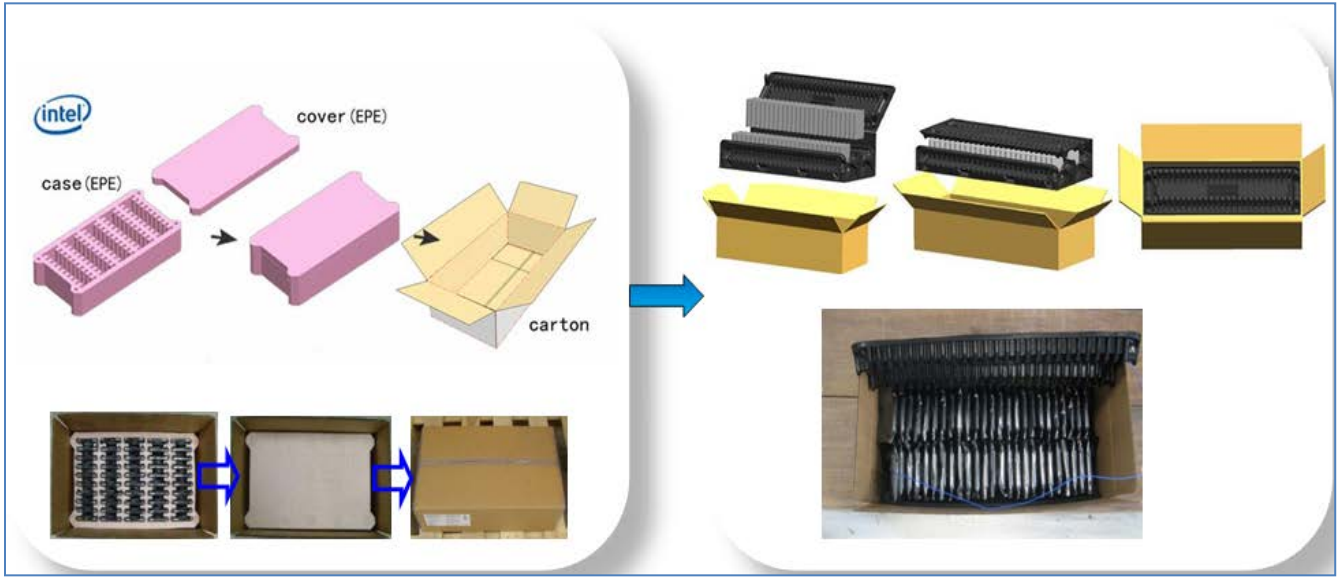
Date Customer Must be Ready to Receive Post-Conversion Material:	Oct 25, 2012

Description of Change to the Customer:

Reason for Revision: To Notify Additional Customers

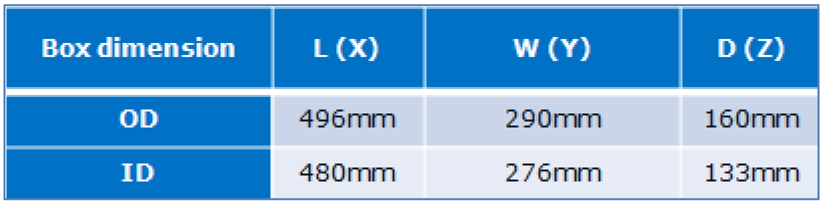
Intel is upgrading the packaging cushion material of the Intel® SSD 710 Series and the Intel® SSD 320 Series from Molded Expandable Polyethylene to Thermoformed HDPE. See below.

OLD Molded Expandable Polyethylene **NEW** Thermoformed HDPE



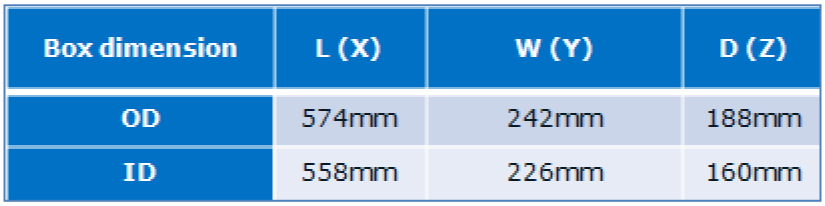
As a result of the cushion material change, the box and pallet dimensions will change as indicated below.

OLD Box Dimensions



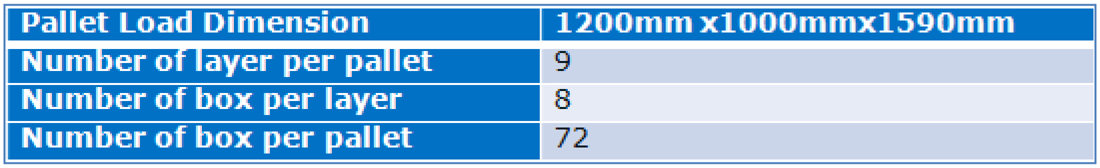
Box dimension	L (X)	W (Y)	D (Z)
OD	496mm	290mm	160mm
ID	480mm	276mm	133mm

NEW Box Dimensions

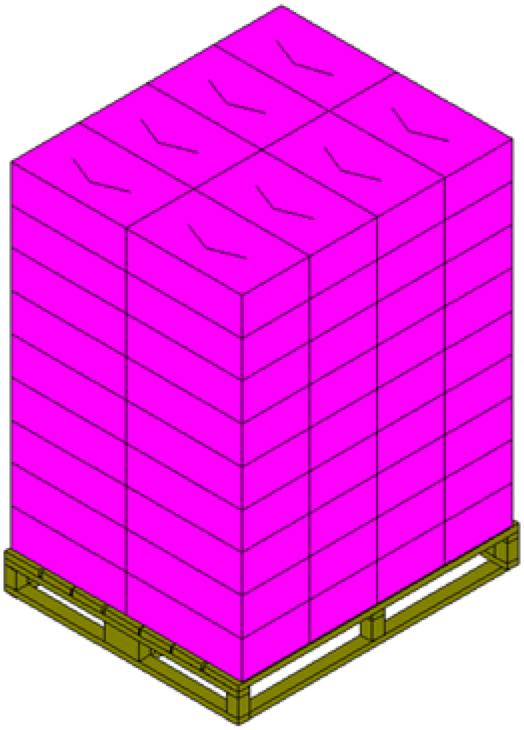


Box dimension	L (X)	W (Y)	D (Z)
OD	574mm	242mm	188mm
ID	558mm	226mm	160mm

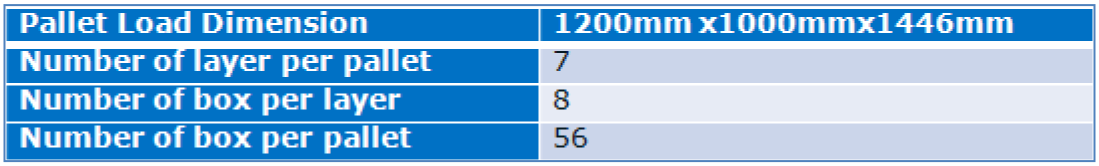
OLD Pallet Dimensions



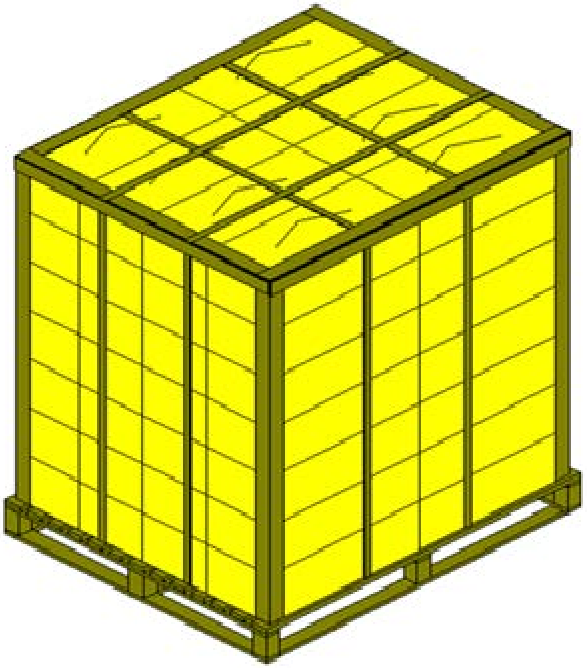
Pallet Load Dimension	1200mm x1000mmx1590mm
Number of layer per pallet	9
Number of box per layer	8
Number of box per pallet	72



NEW Pallet Dimensions



Pallet Load Dimension	1200mm x1000mmx1446mm
Number of layer per pallet	7
Number of box per layer	8
Number of box per pallet	56



Customer Impact of Change and Recommended Action:

Intel will convert to the new packaging material on or after the above date. Customers should be prepared to receive mixed shipments of both the current packaging material and new packaging material until the current packaging material has been depleted.

Intel anticipates no impact to customers; however, they may want to notify their Receiving Departments of the change in the box and pallet dimensions.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
SSDSA2BZ100G3	915126	G32907-603	G32907-604
SSDSA2BZ200G3	915128	G32909-603	G32909-604
SSDSA2BZ300G3	915130	G32911-603	G32911-604
SSDSA2BT040G3	916321	G33011-603	G33011-604
SSDSA2BW080G3	916322	G33018-603	G33018-604
SSDSA2BW160G3	916323	G33020-603	G33020-604
SSDSA2BW300G3	916324	G33014-603	G33014-604
SSDSA2BW600G3	917572	G37538-603	G37538-604
SSDSC2BW120A3	921367	G57557-300	G57557-301
SSDSA2BW120G3	918013	G39388-603	G39388-604
SSDSC2BW180A3	923205	G70115-300	G70115-301
SSDSC2BW240A3	923207	G70118-300	G70118-301
SSDSC2BW060A3FE	923191	G68961-300	G68961-301
SSDSC2BW120A3FE	923192	G68964-300	G68964-301
SSDSC2BW180A3FE	923193	G68966-300	G68966-301
SSDSC2BW240A3FE	923194	G68968-300	G68968-301
SSDSC2BW480A3FE	923195	G68970-300	G68970-301

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
August 14, 2012	00	Originally Published PCN
October 23, 2012	01	To Notify Additional Customers